



Product End-of-Life Disassembly Instructions

Product Category: Other Products

Marketing Name / Model

[List multiple models if applicable.]

HP R7KVA UPS,4U,50A HV NA/JPN KIT AF462A

HP R7KVA UPS,4U,IEC309-32A HV INTL KIT AF463A

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	6
Batteries	All types including standard alkaline and lithium coin or button style batteries	18
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	
Cathode Ray Tubes (CRT)		
Capacitors / condensers (Containing PCB/PCT)		
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		3
External electrical cables and cords		1(NA/JPN) 3(INTL)
Gas Discharge Lamps		
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)		
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	

Components and waste containing asbestos		
Components, parts and materials containing refractory ceramic fibers		
Components, parts and materials containing radioactive substances		

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

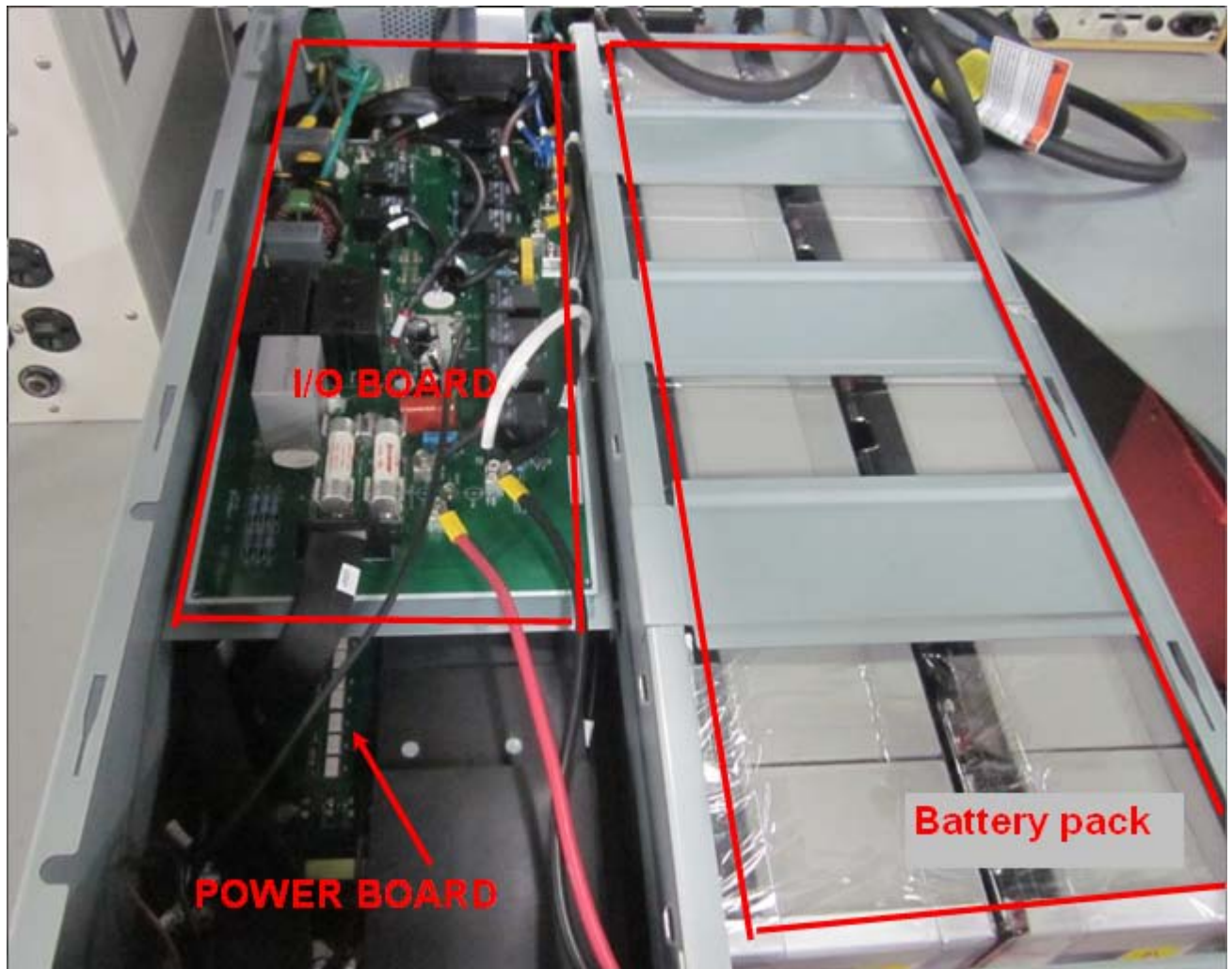
Tool Description	Tool Size (if applicable)
Philips Screwdriver	#2
Hex Driver	3/16
Heavy Wire Cutters	
Flat Head Screwdriver	
Pliers	

3.0 Product Disassembly Process

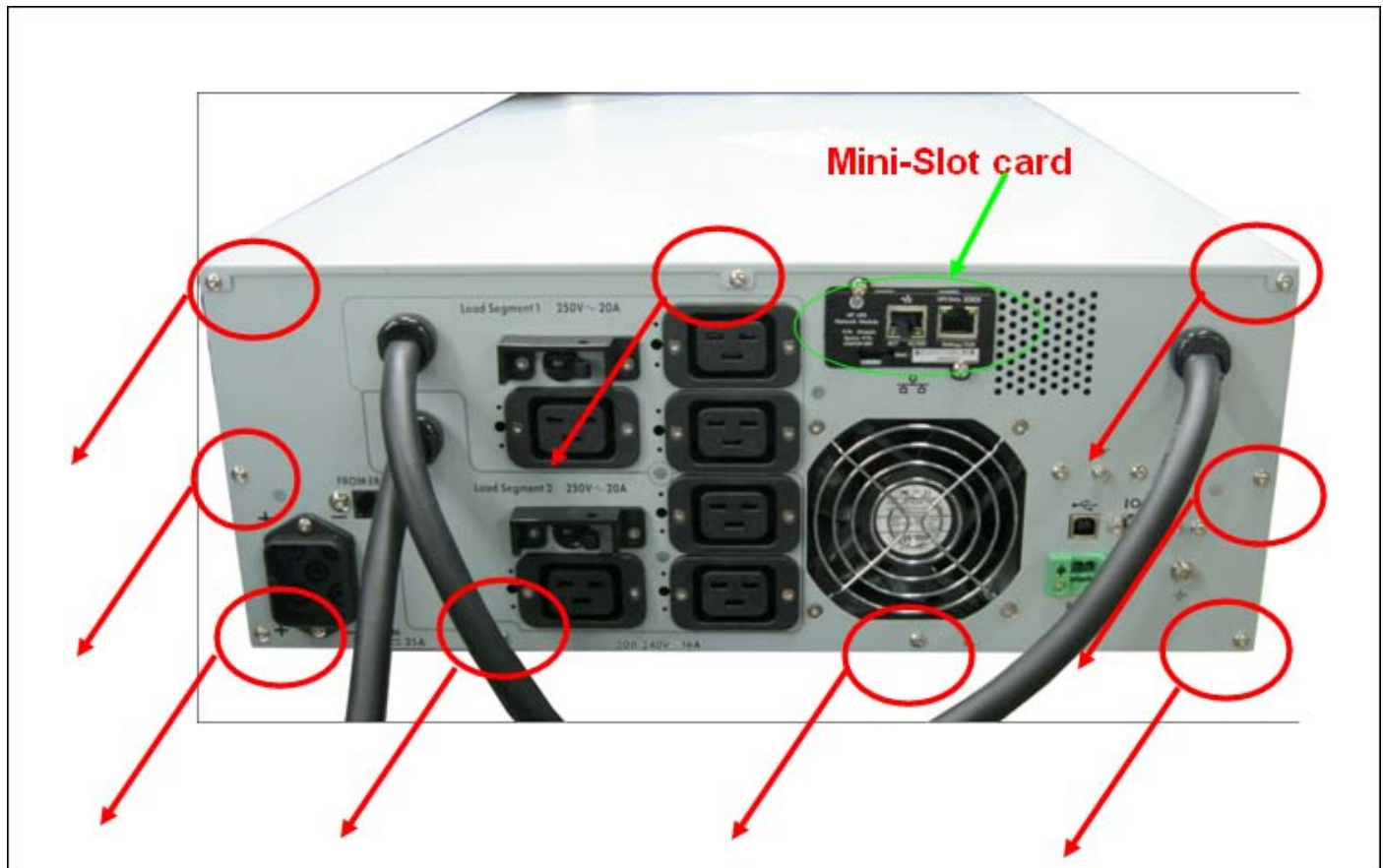
3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Remove front bezel
2. Disconnect and remove the two battery packs
3. Remove Mini-Slot card and dispose of properly (if applicable--Philips screwdriver)
4. Remove top cover (Philips screwdriver)
5. Remove IO Board (Philips screwdriver)
6. Disconnect Control Board connections and remove Control Board (Philips screwdriver)
7. Disconnect Power Board connections and remove Power Board (Philips screwdriver)
8. Remove 3 tall capacitors from Power Board and dispose of components properly (Flat head screwdriver)
9. Remove Rear Panel and cut external power cord if applicable (Philips screwdriver, wire cutters)
10. Remove Comm Board from Rear Panel (Philips screwdriver, hex driver, wire cutters)
11. Disassemble battery pack

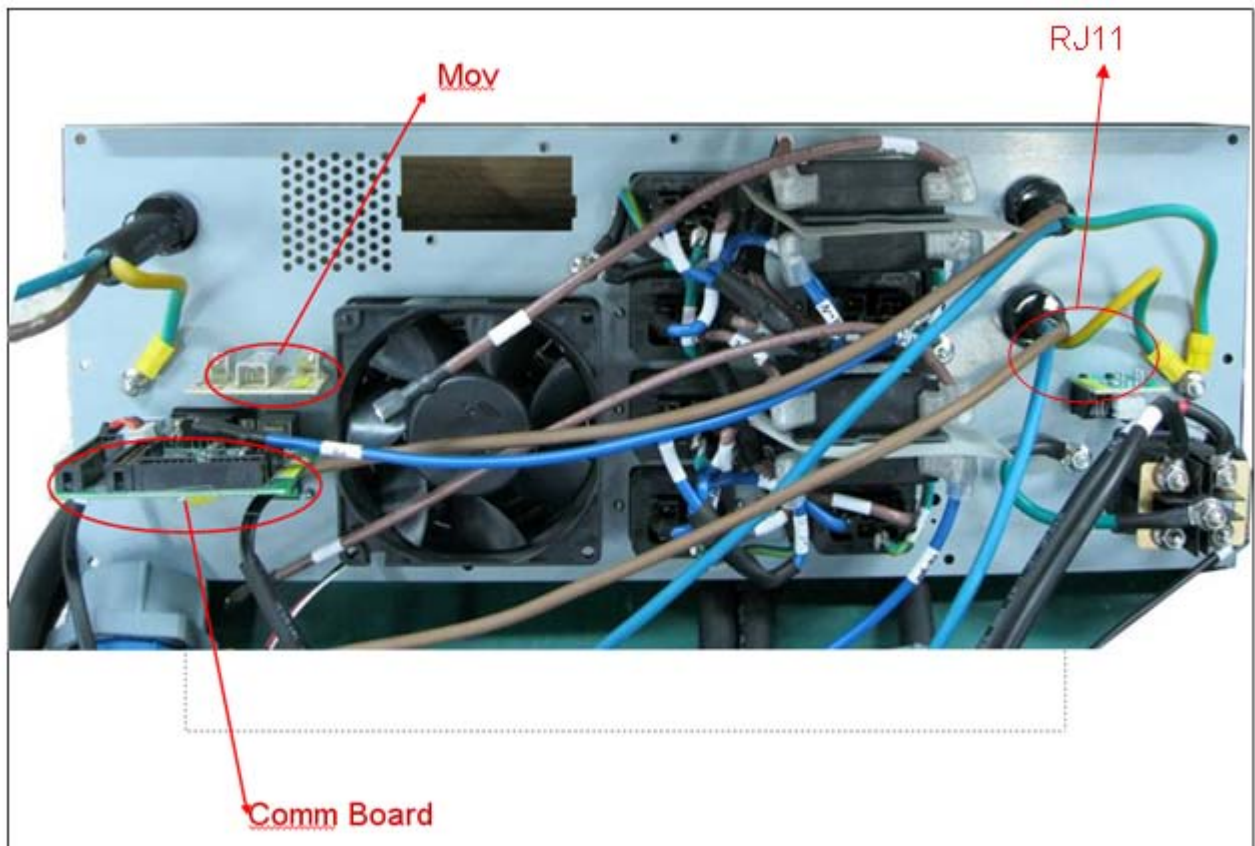
3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).



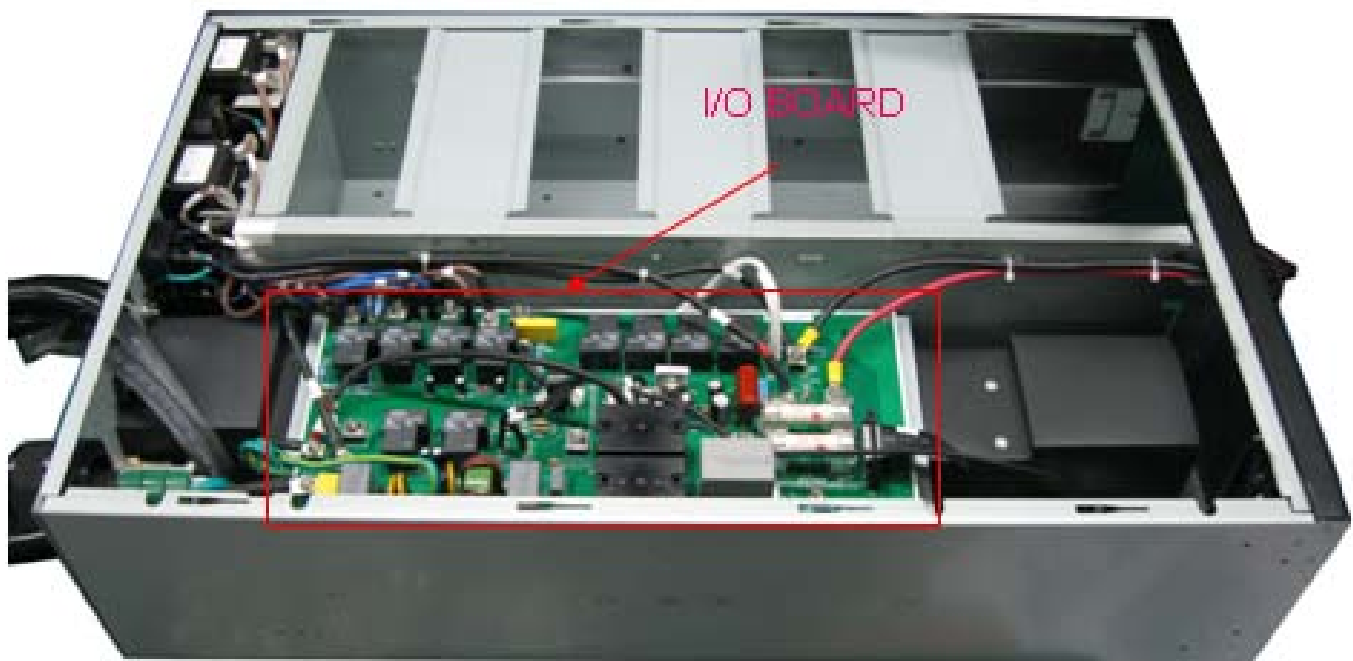
unit component placement



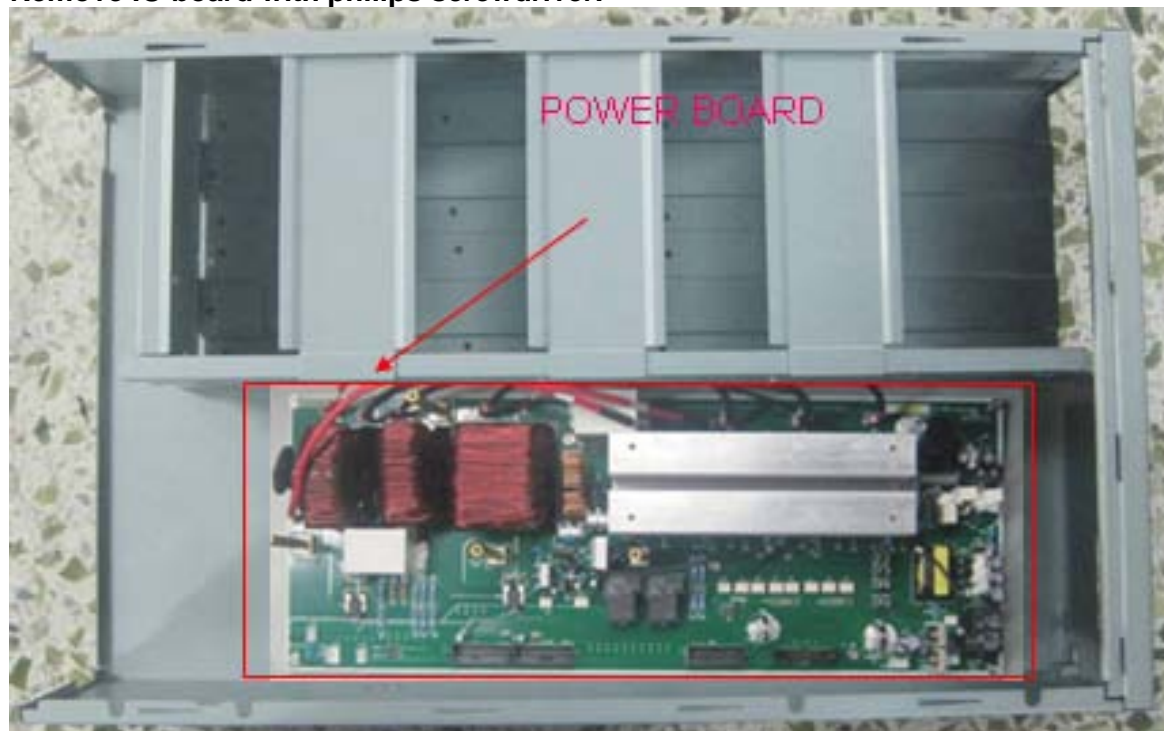
Remove Rear Panel screws, and remove Rear Panel from chassis. Remove Mini-Slot card from slot , and cut power cord with heavy wire cutters.



Using screwdriver and hexdriver, remove Comm Board, Mov Board and RJ11 Board from Rear Panel



Remove IO board with philips screwdriver.



Remove Power board with philips screwdriver.

Capacitors greater than 2.5cm



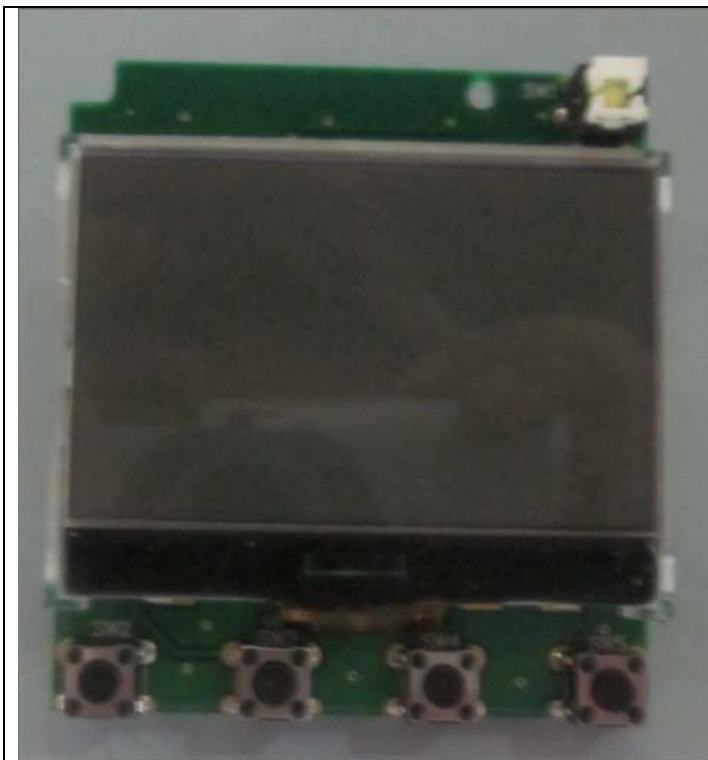
Stucco Power Board Assembly. Remove capacitors greater than 2.5cm with flathead screwdriver.



I/O board.



Mini-Slot card



Display PCB



Communication board



Control board

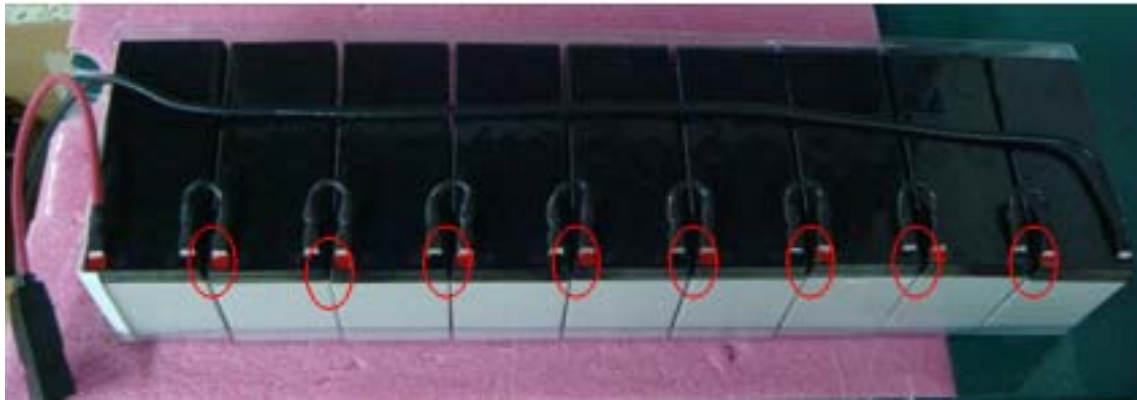


Using pliers, disassemble battery pack. Remove Fuse Board by cutting it away with wire cutters. Fuse Board is wrapped in heat shrink



Using pliers, disassemble battery pack. Remove Fuse Board by cutting it away with wire

cutters. Fuse Board is wrapped in heat shrink



Remove terminals from each battery. Dispose of batteries properly at a local recycling/reuse or hazardous waste center.